

Hong Kong-Shenzhen Innovation and Technology Park Limited

Tender Notice

1. Tender Reference Numbers

- (a) BD-ITT-26-06i-P1&P17 (for Sites P1 and P17)
- (b) BD-ITT-26-06i-P3b&P18 (for Sites P3b and P18)

2. Overview

Hong Kong-Shenzhen Innovation and Technology Park Limited (“**HSITPL**”) invites tenderers to submit a tender for the development of the following site(s) of Batches 2 and 3 of Hong Kong-Shenzhen Innovation and Technology Park (collectively, the “**Sites**” and each a “**Site**”):-

- (a) Site P1 (with the option to submit a tender in respect of Site P17); and
- (b) Site P3b (with the option to submit a tender in respect of Site P18).

Under a public-private-partnership development model, the successful tenderer shall be responsible for the design, construction, financing and management of the development of the Site(s). Please refer to the invitation to tender (the “**Invitation**”) for more details.

3. Tender Process

The tentative timetable is shown in the table below:-

Tender Process	Tentative Date
Issue of Invitation	9 June 2026
Deadline on receiving tender enquiries	17 August 2026
Tender submission period	24 to 28 August 2026 and 31 August 2026
Closing date for submissions of tender by tenderers	31 August 2026
Award by issuing a letter of acceptance to the successful tenderer	Mid-October 2026

Please refer to the Invitation for more details on tender submission requirements.

4. Request for Invitation to Tender

Please complete the **Annex** of this tender notice and return to hsitp.tender@kpmg.com for collection of the Invitation. A formal invitation letter with the Invitation will be sent by e-mail upon receipt of the completed **Annex** of this tender notice by HSITPL or its representatives.

PERSONAL INFORMATION COLLECTION STATEMENT

The information collected from you will be used for the purpose of processing your request for the Invitation to Tender. Your information will not be disclosed by us to any other party in a form that would identify you. You have the right to request access to and correction of information about you held by us. In case you wish to access or correct your personal data held by us, please email privacy@hsitp.org. For details, please refer to our [Personal Information Collection Statement](#).

REQUEST FOR INVITATION TO TENDER

To: Hong Kong-Shenzhen Innovation and Technology Park Limited

Dear Sir / Madam,

- (a) Development of Site P1 (and Site P17, if applicable) of Batches 2 and 3 of Hong Kong-Shenzhen Innovation and Technology Park
- (b) Development of Site P3b (and Site P18, if applicable) of Batches 2 and 3 of Hong Kong-Shenzhen Innovation and Technology Park

We refer to the Tender Notice. We would like to request for collection of the Invitation of the development of the below Site(s). Please put a ✓ where applicable.

Tender reference number	Sites	(You may choose one or more options)
BD-ITT-26-06i-P1&P17	P1 and P17	: <input type="checkbox"/>
BD-ITT-26-06i-P3b&P18	P3b and P18	: <input type="checkbox"/>

Please send us the relevant documents for our onward submission of tender.

From (Company Name) : _____

Signature : _____
(Authorized Signature)

Capacity of the Signatory : _____

Date : _____

Office Address : _____

Email Contact : _____

Phone Number : _____

Business Card of Contact Person :

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